

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 6,883,574 B2  
APPLICATION NO. : 10/633926  
DATED : April 26, 2005  
INVENTOR(S) : Gregory M. Chapman

Page 1 of 9

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

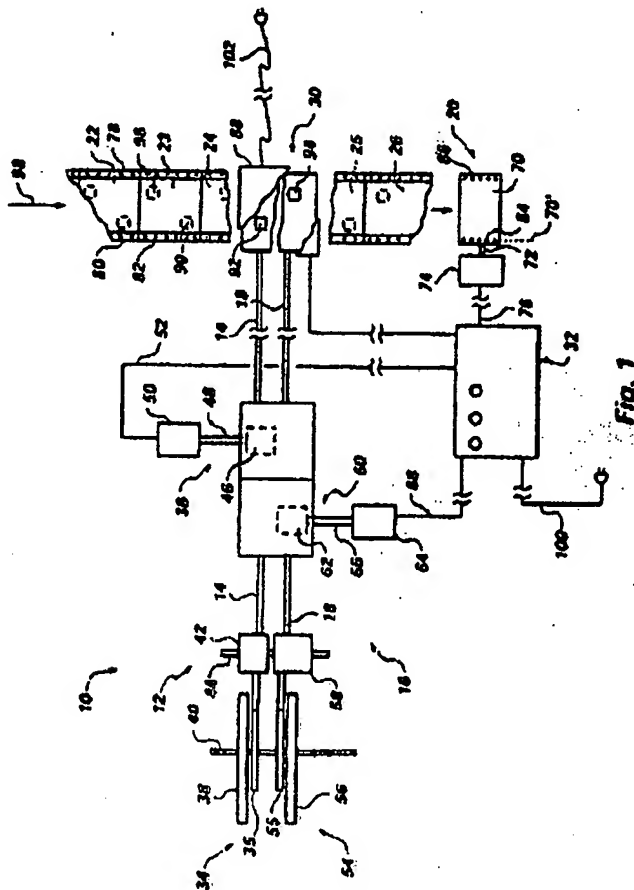
The Title Page showing an illustrative figure, should be deleted and substitute therefor the attached title page.

**On the title page:**  
Item (54) "Title",

change "APPARATUS FOR APPLICATION OF  
ADHESIVE TAPE TO SEMICONDUCTOR DEVICES"  
to --METHOD AND APPARATUS FOR APPLICATION  
OF ADHESIVE TAPE TO SEMICONDUCTOR  
DEVICES--

**In the drawings:**  
In FIG. 1,

change existing lead line for reference numeral --86-- to  
accurately extend from teeth on right side of indexing roller  
70 (As shown below)



PLEASE  
SCAN  
NEW  
TITLE  
PAGE  
ATTACHED  
(NEW PAGE 9&9)

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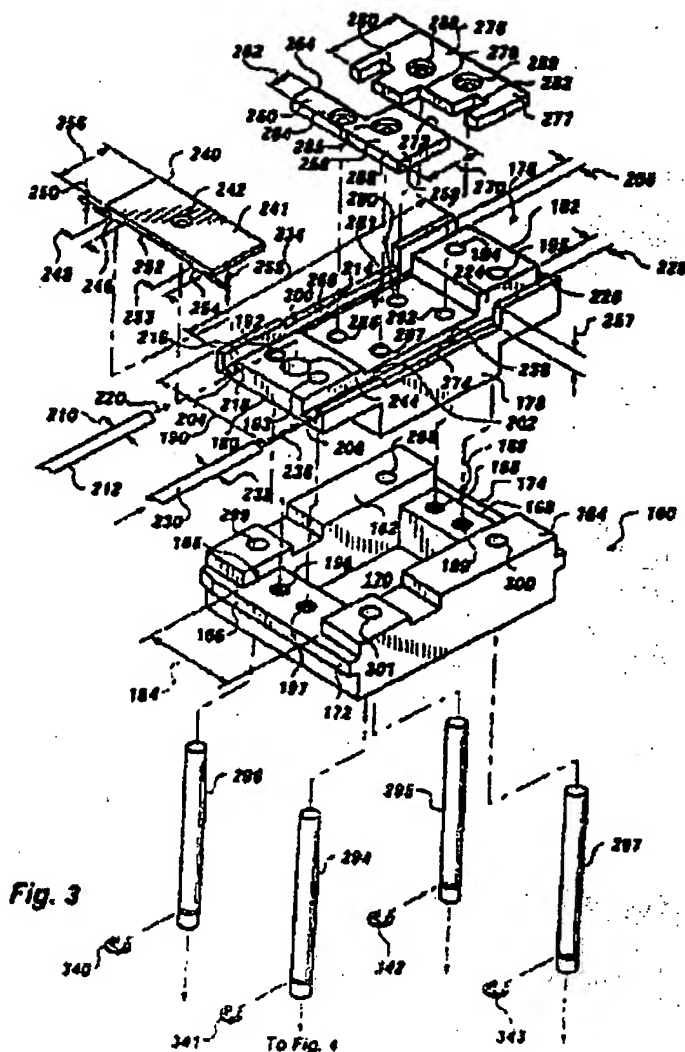
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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

**In FIG. 3,**

change lowermost second occurrence of reference numeral  
"260" located below reference numeral 290 to --261--;  
add reference numeral --184-- and an appropriate lead line  
to indicate a distance  
change first occurrence of reference numeral "341"  
located below guide post 296, to --340-- (As shown below)



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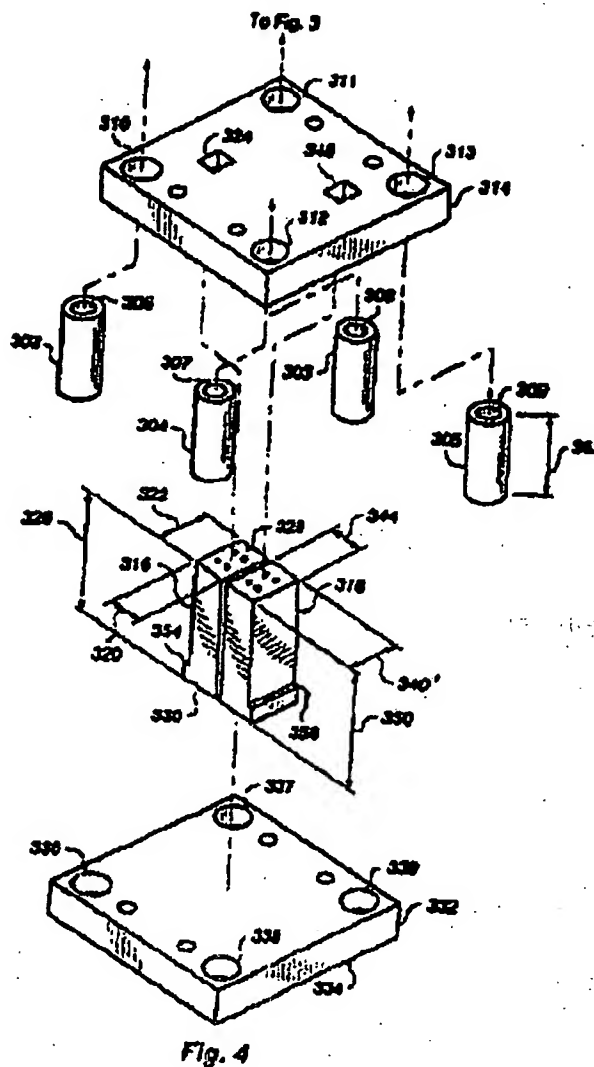
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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

**In FIG. 4,**

change reference numeral "340" to --340'-- (As shown below)



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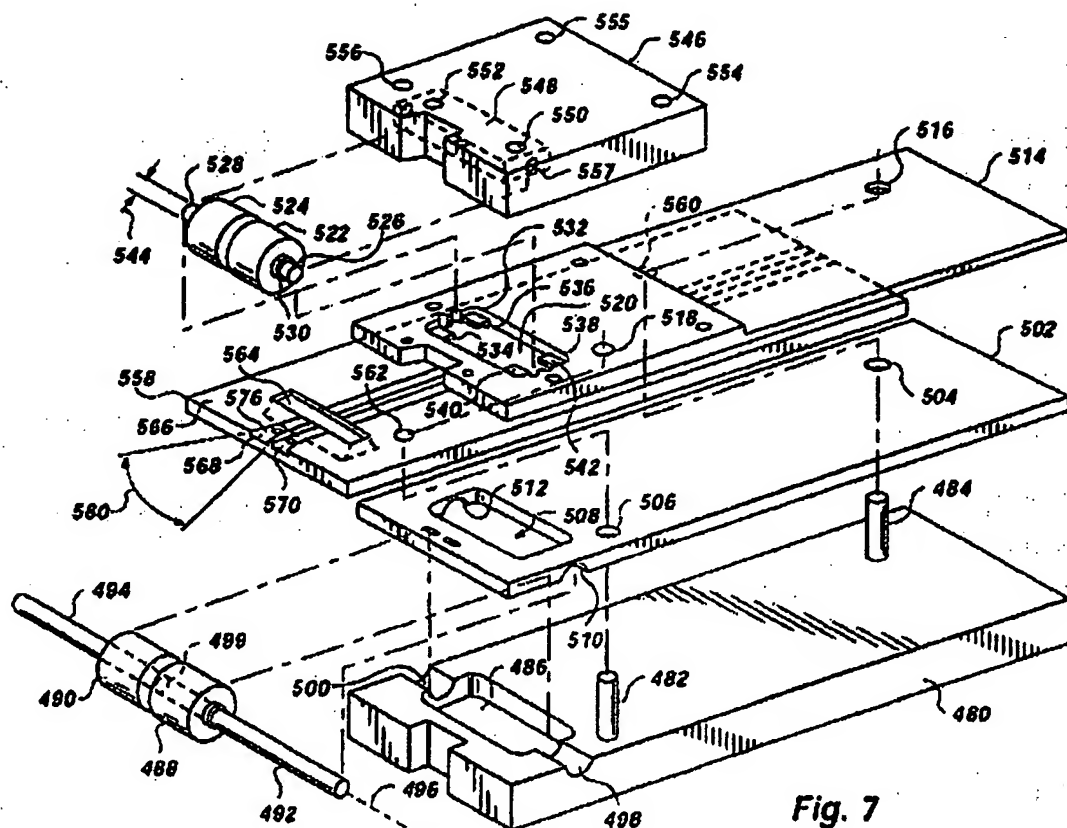
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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

**In FIG. 7,**

add reference numeral --562-- and associated lead line to aperture located left of reference numeral 540 (As shown below)



**Fig. 7**

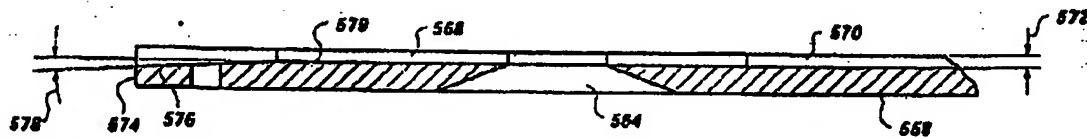
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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

**In FIG. 12,**                      add reference numeral --568-- and an appropriate lead line (As shown below)



**Fig. 12**

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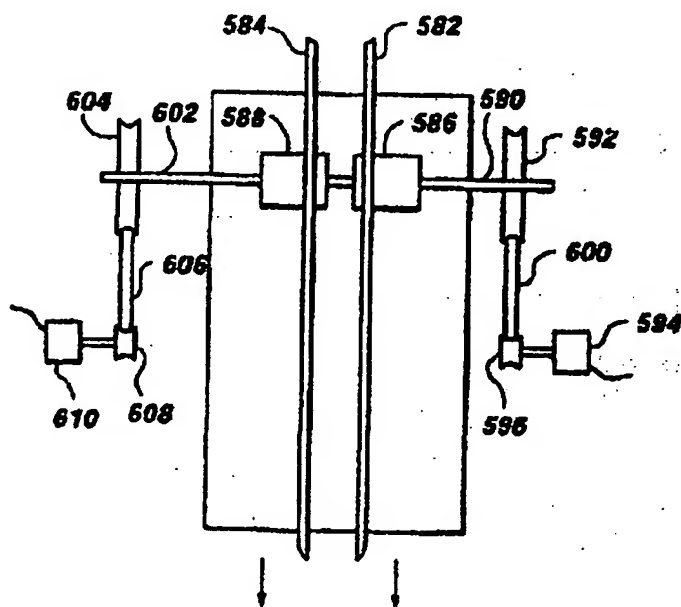
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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

**In FIG. 13,**

add reference numeral--592-- and an appropriate lead line (As shown below)



**Fig. 13**

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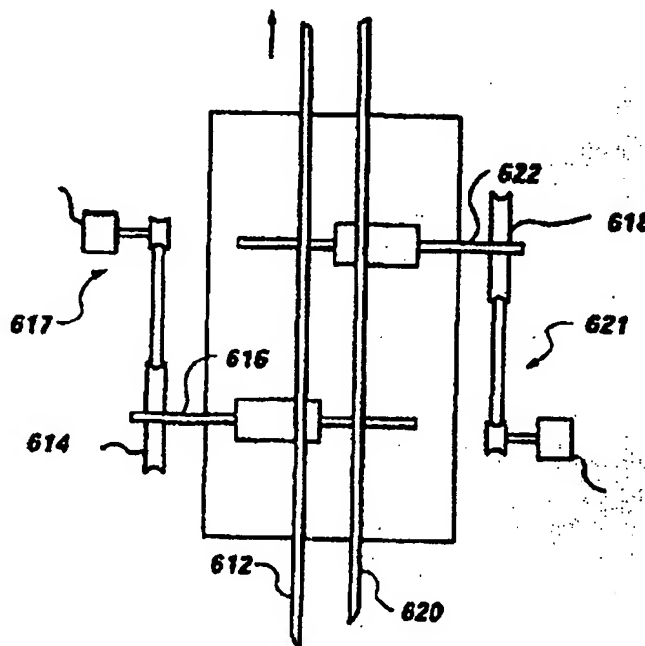
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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

**In FIG. 14,**

move existing reference numeral "618" and associated lead line to far right upper side of drawing, with lead line for --618-- extending from portion adjacent to 622;  
move existing reference numeral "614" and associated lead line to far lower left side of drawing, with lead line for --614-- extending from portion adjacent to 616;  
delete lead lines with out reference numerals (As shown below)



**Fig. 14**

COLUMN 1, LINE 1,

change "APPARATUS FOR APPLICATION OF  
ADHESIVE TAPE TO SEMICONDUCTOR  
DEVICES" to --METHOD AND APPARATUS FOR  
APPLICATION OF ADHESIVE TAPE TO  
SEMICONDUCTOR DEVICES--

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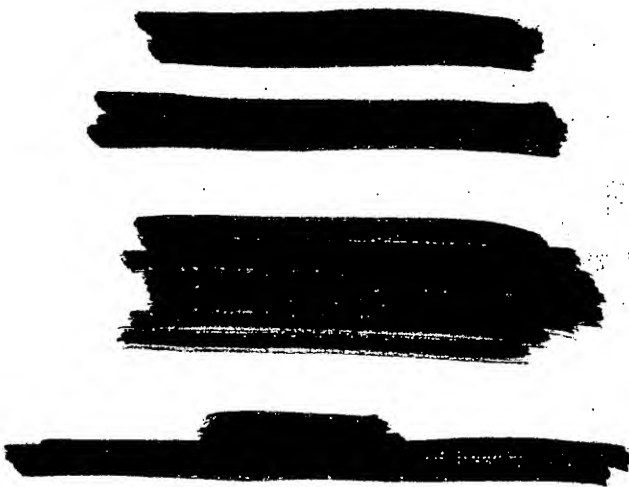
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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

COLUMN 1, LINE 47, change "lead-over-chip" to --lead-over-chip--  
COLUMN 7, LINE 52, after "die site" and before "of" insert --96--  
COLUMN 9, LINE 20, change "thought he" to --through the--  
COLUMN 10, LINE 24, change "show" to --shown--  
COLUMN 11, LINE 8, change "rear cross member" to --rear cross member  
168--  
COLUMN 13, LINE 57, change "rings 341-343" to --rings 340-343--  
COLUMN 13, LINE 59, change "length 340" to --length 340'--  
COLUMN 14, LINE 6, change "340" to --340'--  
COLUMN 14, LINE 8, change "340" to --340'--  
COLUMN 14, LINE 15, change "bushings 302-315" to --bushings 302-305--  
COLUMN 17, LINE 58, change "along right" to --along the right--

This certificate supersedes certificate of correction  
issued March 3, 2009.





US006883574B2

(12) **United States Patent**  
**Chapman**

(10) Patent No.: **US 6,883,574 B2**  
(45) Date of Patent: **Apr. 26, 2005**

(54) **METHOD AND APPARATUS FOR APPLICATION OF ADHESIVE TAPE TO SEMICONDUCTOR DEVICES**

(75) Inventor: **Gregory M. Chapman, Meridian, ID (US)**

(73) Assignee: **Micron Technology, Inc., Boise, ID (US)**

(\*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

(21) Appl. No.: **10/633,926**

(22) Filed: **Aug. 4, 2003**

(65) **Prior Publication Data**

US 2004/0026044 A1 Feb. 12, 2004

**Related U.S. Application Data**

(60) Continuation of application No. 09/875,632, filed on Jun. 6, 2001, now Pat. No. 6,607,019, which is a continuation of application No. 09/330,794, filed on Jun. 14, 1999, now Pat. No. 6,267,167, which is a division of application No. 08/908,291, filed on Aug. 7, 1997, now Pat. No. 6,096,165.

(51) Int. Cl.<sup>7</sup> ..... **B32B 31/00**

(52) U.S. Cl. .... **156/433; 156/511; 156/517; 156/521**

(58) Field of Search ..... **156/355, 433, 156/516, 517, 521, 511; 438/111, 112, 118, 123**

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*Primary Examiner*—John T. Haran

(74) *Attorney, Agent, or Firm*—TraskBritt

(57) **ABSTRACT**

A method and apparatus for application of adhesive tape to semiconductor devices are disclosed. A first adhesively coated tape material length is supplied to a first die associated with a cutting and application mechanism. A second length of adhesively coated tape material is also provided to a second die of the cutting and application mechanism. A plurality of LOC leadframes is supplied sequentially through the application structure to apply a first decal cut from the first tape material to a first die site at a first location and to apply a second decal cut from the second tape material to a second die site at a second location.

**27 Claims, 13 Drawing Sheets**

